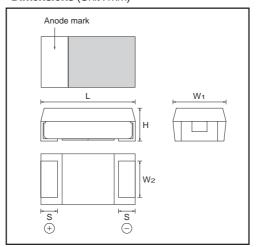
Chip tantalum capacitors with (Fail-safe open structure type)

TCFG series C Case

Features

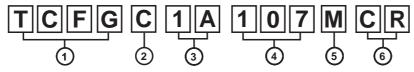
- 1) Safety design by open function built in.
- 2) Wide capacitance range
- 3) Screening by thermal shock.

●Dimensions (Unit:mm)



Case code	L	W ₁	W ₂	Н	S
C 6032-27(2412)	6.0±0.2	3.2±0.2	2.2±0.1	2.5±0.2	1.3±0.2

●Part No. Explanation



- 1 Series name
- 2 Case code
- 3 Rated Voltage

ı	Rated voltage (V)	4	6.3	10	16
ı	CODE	0G	OJ	1A	1C

4 Capacitance

Nominal capacitance in pF in 3 digits: 2 significant figure representing the number of 0's.

- 5 Capacitance tolerance
 - M: ±20%
- 6 Taping
 - C : Tape width (12mm)
 - R : Positive electrode on the side opposite to sprocket hole

● Capacitance range

TCFG series

	Rated voltage (V)						
(μ F)	4 0G	6.3 0J	10 1A	16 1C	20 1D		
22 (226)							
33 (336)							
47 (476)				С			
68 (686)							
100 (107)			С				
150 (157)		С					
220 (227)	C *						

Remark) Case size codes (C) in the above show each size products line-up.

Marking

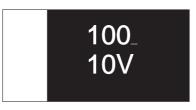
The indications listed below should be given on the surface of a capacitor.

- ① Polarity : The ② Rated DC voltage : The polarity should be shown by \square bar. (on the anode side)
- 3 Nominal capacitance

[C Case] note 1) Visual typical example (1) capacitance code (2) voltage code

(1) $100 \mu F$

(2) 10V



note 2) voltage code and capacitance code are variable with parts number

Characteristics

ltem	Item Performance			Test conditions (based on JIS C5101-1 and JIS C5101-3)					
Operating Temperature			Voltage reduction when temperature exceeds +85°C						
Maximum operatin with no voltage de		+8	5 °C						
Rated Voltage (V.DC) 4 6.3 10 16				at 85°C					
Category Voltage	ge (V.DC)	2.5	4	6.3	10		at 125°C		
Surge Voltage		5.0	8	13	20		at 85°C		
DC leakage cui	rrent					/ whichever is greater dard list")	As per 4.9 JIS C 5101-1 As per 4.5.1 JIS C 5101-3 Voltage : Rated voltage for 1 min		
Capacitance tolerance			Shall be satisfied allowance range. ±20%		allowance range.	As per 4.7 JIS C 5101-1 As per 4.5.2 JIS C 5101-3 Measuring frequency : 120±12Hz Measuring voltage : 0.5Vrms, +1.5 to 2V.DC Measuring circuit : DC Equivalent series circu			
Tangent of loss angle (Df, $tan\delta$)			Shall be satisfied the voltage on "Standard list"		the voltage on "Standard list	t" As per 4.8 JIS C 5101-1 As per 4.5.3 JIS C 5101-3 Measuring frequency : 120±12Hz Measuring voltage : 0.5Vrms, +1.5 to 2V.DC Measuring circuit : DC Equivalent series circu			
Impedance			Shall be satisfied the voltage on "Standard list"		the voltage on "Standard list	As per 4.10 JIS C 5101-1 As per 4.5.4 JIS C 5101-3 Measuring frequency : 100±10kHz Measuring voltage : 0.5Vrms or less Measuring circuit : DC Equivalent series circuit			
Resistance to soldering heat		There should be no significant abnormality. The indications should be clear.					As per 4.14 JIS C 5101-1 As per 4.6 JIS C 5101-3		
Ü	L.C	Less than initial limit Within ±10% of initial value			itial I	mit	Dip in the solder bath		
	ΔC / C				6 of i	nitial value	Solder temp : 260±5°C Duration : 5±0.5s		
	tanδ	Less than 150% of initial limit			50%	of initial limit	Repetition : 1 After the specimens, leave it at room temperature over 24h and then measure the sample.		
Fail-Safe open u	unit actuation	Within 320°C – 20s			C – :	20s	Dip in the solder bath Solder temp : 330±5°C		
Temperature cycle	Appearance	There should be no significant abnormality.			d be	no significant abnormality.	As per 4.16 JIS C 5101-1 As per 4.10 JIS C 5101-3		
	L.C	Les	ss th	an in	itial I	imit	Repetition: 5 cycles (1 cycle: steps 1 to 4)		
	ΔC / C	Wit	thin ±	20%	6 of i	nitial value	without discontinuation.		
	tanδ	Less than 150% of initial limit		of initial limit	Step Temp. Time				
Moisture resistance	Appearance	l				no significant abnormality. hould be clear.	As per 4.22 JIS C 5101-1 As per 4.12 JIS C 5101-3		
	L.C	Les	ss th	an in	itial I	mit	After leaving the sample under such atmosphe		
	ΔC / C	Wi	thin ±	20%	of i	nitial value	condition that the temperature and humidity are 60±2°C and 90 to 95%RH, respectively, for		
		Less than 150% of initial limit					500±24h level it at room temperature for over 24l and then measure the sample.		



Tantalum capacitors

Iten	n	Performance	Test conditions (based on JIS C5101-1 and JIS C5101-3)
Temperature	Temp.	−55°C	As per 4.29 JIS C 5101-1
Stability	ΔC / C	Within 0/–12%of initial value	As per 4.13 JIS C 5101-3
	tanδ	Shall be satisfied the voltage on "Standard list"	
	L.C	_	
	Temp.	+85°C	
	ΔC / C	Within +12/0%of initial value	
	tanδ	Shall be satisfied the voltage on "Standard list"	
	L.C	5μA or 0.1CV whichever is greater	
	Temp.	+125°C	
	ΔC / C	Within +15/0%of initial value	
	tanδ	Shall be satisfied the voltage on "Standard list"	
	L.C	6.3μA or 0.125CV whichever is greater	
Surge	Appearance	There should be no significant abnormality.	As per 4.26 JIS C 5101-1 As per 4.14 JIS C 5101-3
Voltage	L.C	Less than initial value	Apply the specified surge voltage every 5±0.5min.
	ΔC / C	Within ±12%of initial value	for 30±5 s. each time in the atmospheric condition of 85±2°C.
	tanδ	Less than 150% of initial limit	Repeat this procedure 1,000 times. After the specimens, leave it at room temperature for over 24h and then measure the sample.
Loading at	Appearance	There should be no significant abnormality.	As per 4.23 JIS C 5101-1
High temperature	L.C	Less than 125% of initial limit	As per 4.15 JIS C 5101-3 After applying the rated voltage for 2000+72/0h
	ΔC / C	Within ±20%of initial value	without discontinuation via the serial resistance
	tanδ	Less than 150% of initial limit	of 3Ω or less at a temperature of $85\pm2^{\circ}$ C, leave the sample at room temperature/humidity for over 24h and measure the value.
Terminal	Capacitance	The measured value should be stable.	As per 4.35 JIS C 5101-1
Strength	Appearance	There should be no significant abnormality.	As per 4.9 JIS C 5101-3 A force is applied to the terminal until it bends to 1mm and by a prescribed tool maintain the condition for 5s. (See the figure below.) (Unit : mm) F (Apply force) Thickness 1.6mm
Adhesiveness		The terminal should not come off.	As per 4.34 JIS C 5101-1 As per 4.8 JIS C 5101-3 Apply force of 5N in the two directions shown in the figure below for 10±1s after mounting the terminal on a circuit board. product Apply force a circuit board

Tantalum capacitors

It	em	Performance	Test conditions (based on JIS C5101-1 and JIS C5101-3)
Dimensions		Be based on "External dimensions"	Measure using a caliper of JIS B 7505 Class 2 or higher grade.
Resistance to solvents		The indication should be clear.	As per 4.32 JIS C 5101-1 As per 4.18 JIS C 5101-3 Dip in the isopropyl alcohol for 30±5s, at room temperature.
Solderability		3/4 or more surface area of the solder coated terminal dipped in the soldering bath should be covered with the new solder.	As per 4.15.2 JIS C 5101-1 As per 4.7 JIS C 5101-3 Dip speed = 25±2.5mm/s Pre-treatment (accelerated aging): Leave the sample on the boiling distilled water for 1h. Solder temp.: 245±5°C Duration: 3±0.5s Solder: M705 Flux: Rosin 25%, IPA 75%
measurement.		Measure value should not fluctuate during the measurement. There should be no significant abnormality.	As per 4.17 JIS C 5101-1 Frequency: 10 to 55 to 10Hz/min. Amplitude: 1.5mm Time: 2h each in X, Y and Z directions Mounting: The terminal is soldered on a print circuit board.

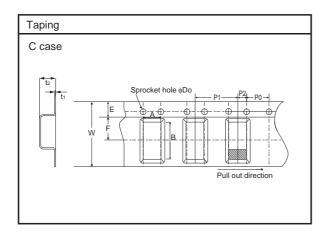
● Table 1 standard list, TCFG series C Case

lable 1 standard list, I CFG series C Case															
										(C	: 6032)				
Part No.	Rated Voltage @85°C	Derated Voltage @125°C	Surge Voltage @85°C	Itage Capacitance 35°C 120Hz	Capacitance Tolorance C		Iz Folerance 25		apacitance Tolerance		D	F 120H (%)	łz	Impedance 100kHz	Case
	(V)	(V)	(V)		(%)	(%) 1WV.60s (μA)	–55°C	25°C 85°C	125°C	(Ω)					
TCFG C 0J 157□	6.3	4	8	150	±20	9.5	30	12	16	1.3	С				
TCFG C 1A 107□	10	6.3	13	100	±20	10.0	14	10	12	1.3	С				
TCFG C 1C 476□	16	10	20	47	±20	7.5	12	8	10	1.6	С				

 \square = Tolerance (M : $\pm 20\%$)

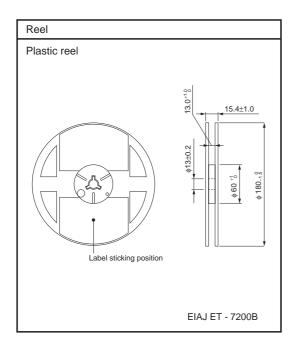
Packaging specifications

	A±0.2	B±0.2	W±0.3	E±0.1	F±0.1	P₁±0.1
Case code	3.7	6.4	12	1.75	5.5	8.0
C (6032)	P ₂ ±0.1	P₀±0.1	D ₀	t₁±0.1	t2±0.2	
	2.0	4.0	φ1.5	0.3	3.0	



Packaging style

Case size	Packaging	Packag	ing style	Symbol	Basic ordering unit
C Case	Taping	Plastic taping	φ180mm reel	R	500



• Recommended condition of reflow soldering

(1) Leakage current-to-voltage ratio

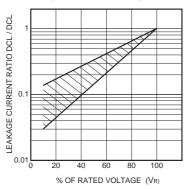
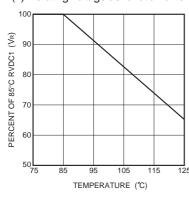


Fig.1

(2) Derating voltage as function of temperature



85	5°C	125	5°C
Rated Voltage	Surge Voltage	Category Voltage	Surge Voltage
(V.DC)	(V.DC)	(V.DC)	(V.DC)
2.5	3.2	1.6	2.0
4	5.0	2.5	3.2
6.3	8	4	5
10	13	6.3	8
16	20	10	13
20	26	13	16
25	32	16	20

Fig.2

(3) Reliability

The malfunction rate of tantalum solid state electrolytic capacitors varies considerably depending on the conditions of usage (ambient temperature, applied voltage, circuit resistance).

Formula for calculating malfunction rate

 $\lambda p = \lambda b \times (\pi E \times \pi SR \times \pi Q \times \pi CV)$

 λp : Malfunction rate stemming from operation

 $\begin{array}{lll} \lambda b & : \mbox{Basic malfunction rate} \\ \pi E & : \mbox{Environmental factors} \\ \pi S R & : \mbox{Series resistance} \\ \pi \Omega & : \mbox{Level of malfunction rate} \\ \end{array}$

 πcv : Capacitance

For details on how to calculate the malfunction rate stemming from operation, see the tantalum solid state electrolytic capacitors column in MIL-HDBK-217.

Malfunction rate as function of operating temperature and rated voltage

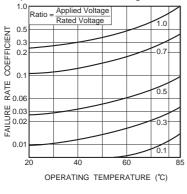
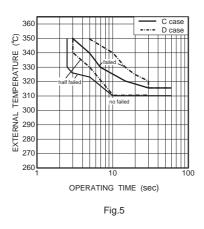


Fig.3

(4) External temperature vs. fuse blowout



Malfunction rate as function of circuit resistance ($\Omega\!/\!V)$

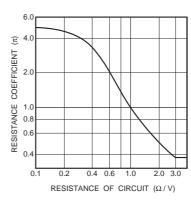


Fig.4

(5) Power vs. fuse blowout characteristics / Product surface temperature

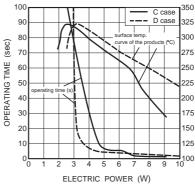


Fig.6

Note: Solder the chip at 300°C or less. If it is soldered using a temperature higher than 300°C, open function built-in may operate.

(6) Maximum power dissipation

Warming of the capacitor due to ripple voltage balances with warming caused by Joule heating and by radiated heat. Maximum allowable warming of the capacitor is to 5°C above ambient temperature. When warming exceeds 5°C, it can damage the dielectric and cause a short circuit.

Power dissipation (P) = $I^2 \cdot R$

Ripple current

 $\ensuremath{\mathsf{P}}$: As shown in table at right

R: Equivalent series resistance

Notes:

- 1. Please be aware that when case size is changed, maximum allowable power dissipation is reduced.
- 2. Maximum power dissipation varies depending on the package. Be sure to use a case which will keep warming within the limits shown in the table below.

Allowable power dissipation (W) and maximum temperature rising

Case Ambient temp.	+25°C	+55°C	+85°C	+125°C
C case (6032)	0.110	0.099	0.088	0.044
Max. Temp Rise[°C]	5	5	5	2

(7) Impedance frequency characteristics

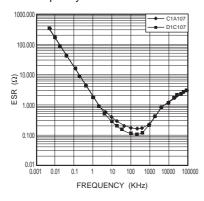


Fig.7

(8) ESR frequency characteristics

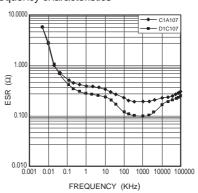


Fig.8

(9) Temperature characteristics

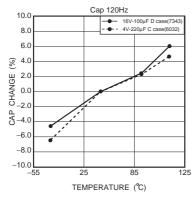


Fig.9

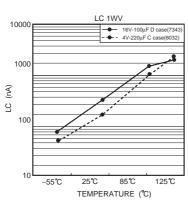


Fig.11

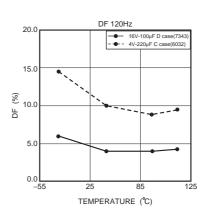


Fig.10

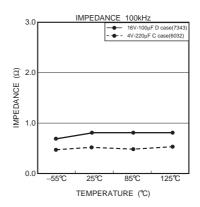


Fig.12



Inrush current

Beware of inrush current.

Inrush currents are inversely proportional ESR. Large inrush currents can cause components failure.

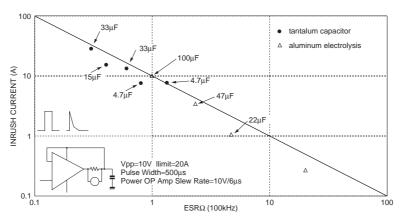


Fig. 13 Maximum inrush current and ESR

Inrush current can be limited by means of a protective resistor.

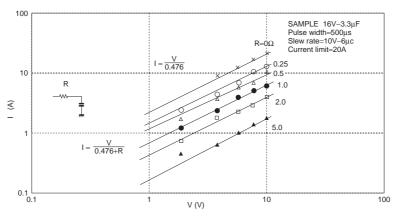


Fig. 14 Imax change due to protective resistor R

(10) Ultrasonic cleaning

Carry out cleaning under as mild conditions as possible. The internal element of a tantalum capacitor are larger than those of a transistor or diode, so it is not as resistant as ultrasonic waves.

Example: water

 $\begin{array}{ll} \mbox{Propagation speed} & \mbox{1500m/s} \\ \mbox{Solvent density} & \mbox{1g/cm}^{3} \end{array}$

Frequency and wavelength

Frequency	Wavelength
20kHz	7.5cm
28kHz	5.3cm
50kHz	3.0cm

Tantalum capacitors

Precautions

- 1) Do not allow solvent to come to a boil (kinetic energy increases).
- . Ultrasonic output 0.5W / cm² or less
- . Use a solvent with a high boiling point.
- . Lower solvent temperature.
- 2) Ultrasonic cleaning frequency 28 kHz or less
- 3) Keep cleaning time as short as possible.
- 4) Move item being cleaned.

 Standing waves caused by the ultrasonic waves can cause stress to build up in part of the item being cleaned.

Reference

 $\label{eq:Kinetic energy} \text{Kinetic energy} = 2 \times \pi \times \text{frequency} \times \sqrt{\frac{2 \times \text{Ultrasonic output}}{\text{propagation} \times \text{speed} \times \text{solvent density}}}$

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